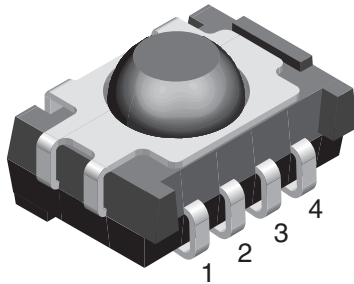


## IR Receiver Modules for Remote Control Systems



16797

### DESIGN SUPPORT TOOLS

[click logo to get started](#)


### MECHANICAL DATA

#### Pinning:

 1 = GND, 2 = N.C., 3 =  $V_S$ , 4 = OUT

### ORDERING CODE

#### Taping:

TSOP36...TT - top view taped

TSOP36...TR - side view taped

### FEATURES

- Very low supply current
- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Continuous data transmission possible
- Supply voltage: 2.5 V to 5.5 V
- Insensitive to supply voltage ripple and noise
- Taping available for topview and sideview assembly
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### DESCRIPTION

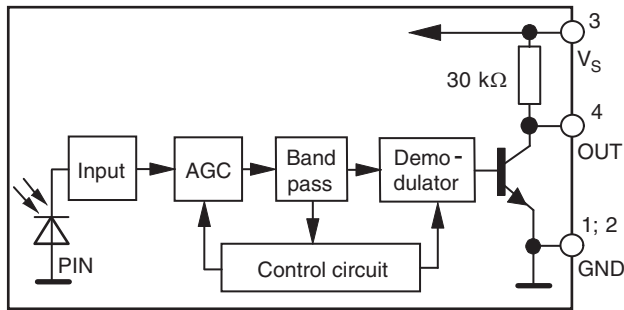
The TSOP361.., TSOP363.., and TSOP365.. series are miniaturized SMD IR receiver modules for infrared remote control systems. PIN diode and preamplifier are assembled on a lead frame, the epoxy package contains an IR filter. The demodulated output signal can be directly connected to a microprocessor for decoding.

The TSOP363.. series devices are optimized to suppress almost all spurious pulses from energy saving lamps like CFLs. AGC3 may also suppress some data signals if continuously transmitted.

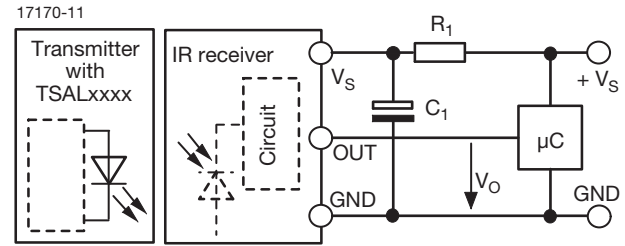
The TSOP361.. series are provided primarily for compatibility with old AGC1 designs. New designs should prefer the TSOP363.. series containing the newer AGC3. The TSOP365.. series contain a very robust AGC5. This series should only be used for critically noisy environments.

These components have not been qualified according to automotive specifications.

PARTS TABLE				
AGC		LEGACY, FOR SHORT BURST REMOTE CONTROLS (AGC1)	NOISY ENVIRONMENTS AND SHORT BURSTS (AGC3)	VERY NOISY ENVIRONMENTS AND SHORT BURSTS (AGC5)
Carrier frequency	30 kHz	TSOP36130	TSOP36330	TSOP36530
	33 kHz	TSOP36133	TSOP36333	TSOP36533
	36 kHz	TSOP36136	TSOP36336 <sup>(1)</sup>	TSOP36536
	38 kHz	TSOP36138	TSOP36338 <sup>(2)(3)(4)(5)</sup>	TSOP36538
	40 kHz	TSOP36140	TSOP36340	TSOP36540
	56 kHz	TSOP36156	TSOP36356	TSOP36556
Package	Panhead			
Pinning	1 = GND, 2 = N.C., 3 = $V_S$ , 4 = OUT			
Dimensions (mm)	7.5 W x 5.3 H x 4.0 D			
Mounting	SMD			
Application	Remote control			
Best choice for	<sup>(1)</sup> MCIR <sup>(2)</sup> Mitsubishi <sup>(3)</sup> RECS-80 Code <sup>(4)</sup> r-map <sup>(5)</sup> XMP-1, XMP-2			

**BLOCK DIAGRAM**


16839

**APPLICATION CIRCUIT**

 $R_1$  and  $C_1$  recommended to reduce supply ripple for  $V_S < 2.8\text{ V}$ 
**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Supply voltage (pin 3)		$V_S$	-0.3 to +6	V
Supply current (pin 3)		$I_S$	3	mA
Output voltage (pin 4)		$V_O$	-0.3 to ( $V_S + 0.3$ )	V
Output current (pin 4)		$I_O$	5	mA
Junction temperature		$T_j$	100	°C
Storage temperature range		$T_{stg}$	-25 to +85	°C
Operating temperature range		$T_{amb}$	-25 to +85	°C
Power consumption	$T_{amb} \leq 85\text{ °C}$	$P_{tot}$	10	mW

**Note**

- Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability

**ELECTRICAL AND OPTICAL CHARACTERISTICS** ( $T_{amb} = 25\text{ °C}$ , unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply current	$E_v = 0, V_S = 3.3\text{ V}$	$I_{SD}$	0.27	0.35	0.45	mA
	$E_v = 40\text{ klx, sunlight}$	$I_{SH}$	-	0.45	-	mA
Supply voltage		$V_S$	2.5	-	5.5	V
Transmission distance	$E_v = 0$ , test signal see Fig. 1, IR diode TSAL6200, $I_F = 50\text{ mA}$	$d$	-	24	-	m
Output voltage low	$I_{OSL} = 0.5\text{ mA}, E_e = 0.7\text{ mW/m}^2$ , test signal see Fig. 1	$V_{OSL}$	-	-	100	mV
Minimum irradiance	Pulse width tolerance: $t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$ , test signal see Fig. 1	$E_e\text{ min.}$	-	0.12	0.25	$\text{mW/m}^2$
Maximum irradiance	$t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o$ , test signal see Fig. 1	$E_e\text{ max.}$	30	-	-	$\text{W/m}^2$
Directivity	Angle of half transmission distance	$\phi_{1/2}$	-	$\pm 50$	-	°

**TYPICAL CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

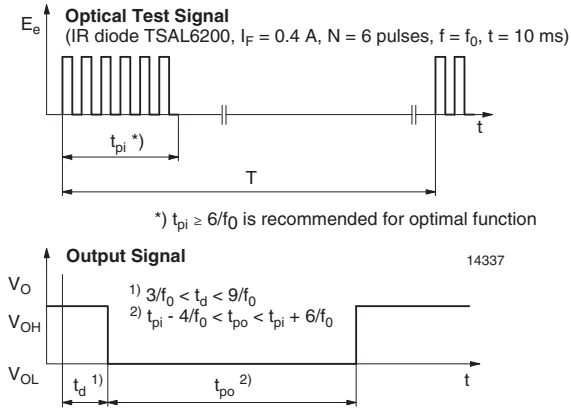


Fig. 1 - Output Function

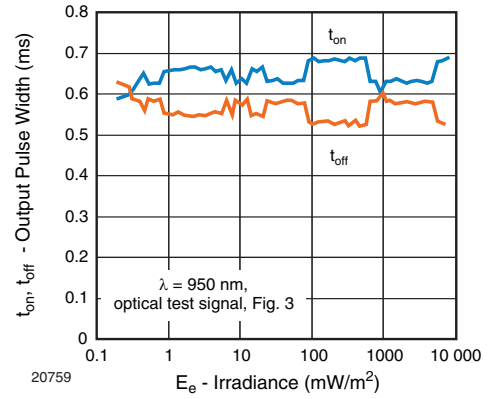


Fig. 4 - Output Pulse Diagram

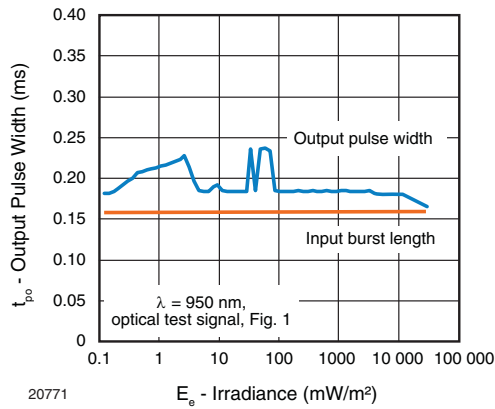


Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

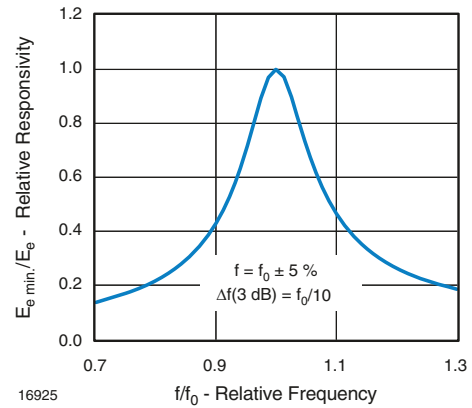


Fig. 5 - Frequency Dependence of Responsivity

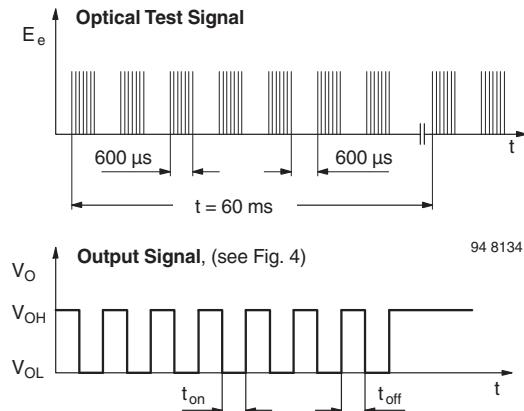


Fig. 3 - Output Function

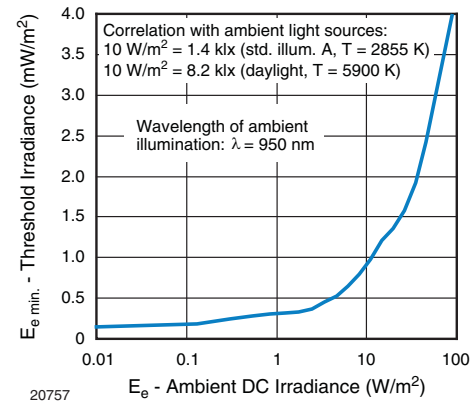


Fig. 6 - Sensitivity in Bright Ambient

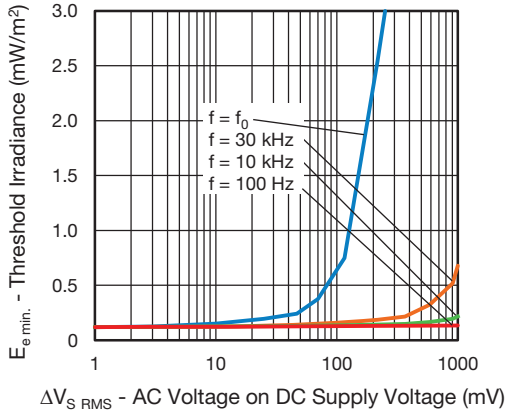


Fig. 7 - Sensitivity vs. Supply Voltage Disturbances

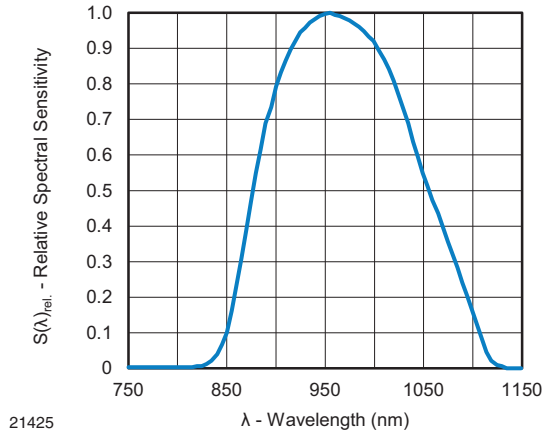


Fig. 10 - Relative Spectral Sensitivity vs. Wavelength

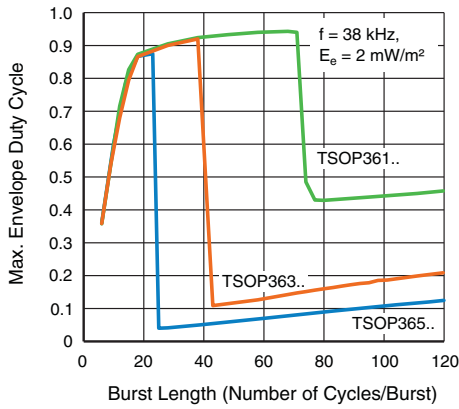


Fig. 8 - Maximum Envelope Duty Cycle vs. Burstlength

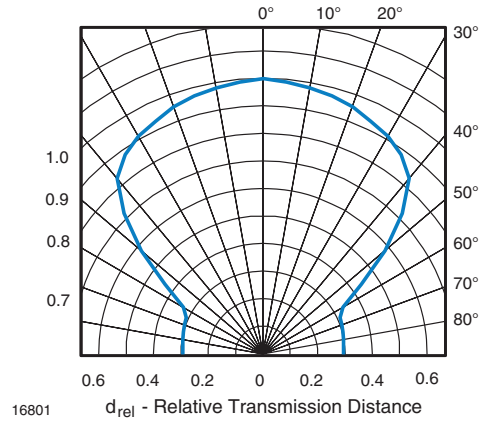


Fig. 11 - Directivity

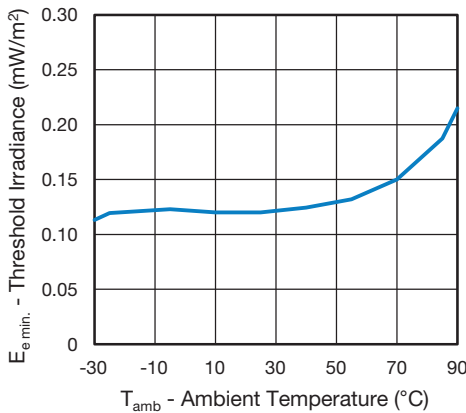


Fig. 9 - Sensitivity vs. Ambient Temperature

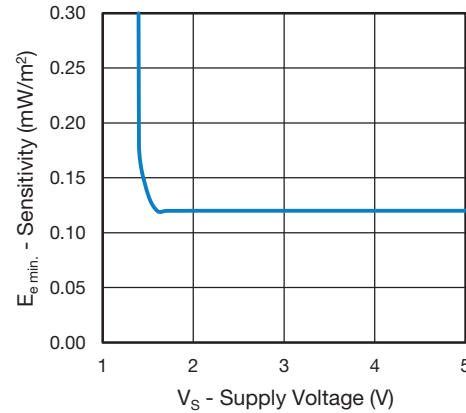


Fig. 12 - Sensitivity vs. Supply Voltage

**SUITABLE DATA FORMAT**

This series is designed to suppress spurious output pulses due to noise or disturbance signals. The devices can distinguish data signals from noise due to differences in frequency, burst length, and envelope duty cycle. The data signal should be close to the device's band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.

When a data signal is applied to the product in the presence of a disturbance, the sensitivity of the receiver is automatically reduced by the AGC to insure that no spurious pulses are present at the receiver's output.

Some examples which are suppressed are:

- DC light (e.g. from tungsten bulbs sunlight)
- Continuous signals at any frequency
- Strongly or weakly modulated patterns from fluorescent lamps with electronic ballasts (see Fig. 13 or Fig. 14)

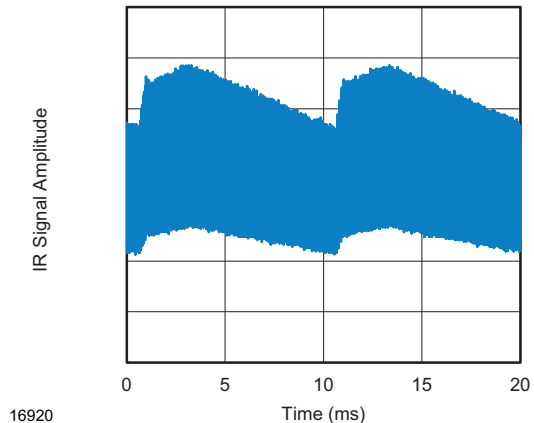


Fig. 13 - IR Signal from Fluorescent Lamp With Low Modulation

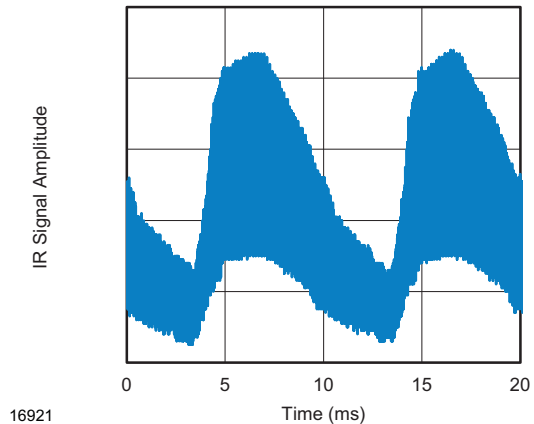


Fig. 14 - IR Signal from Fluorescent Lamp With High Modulation

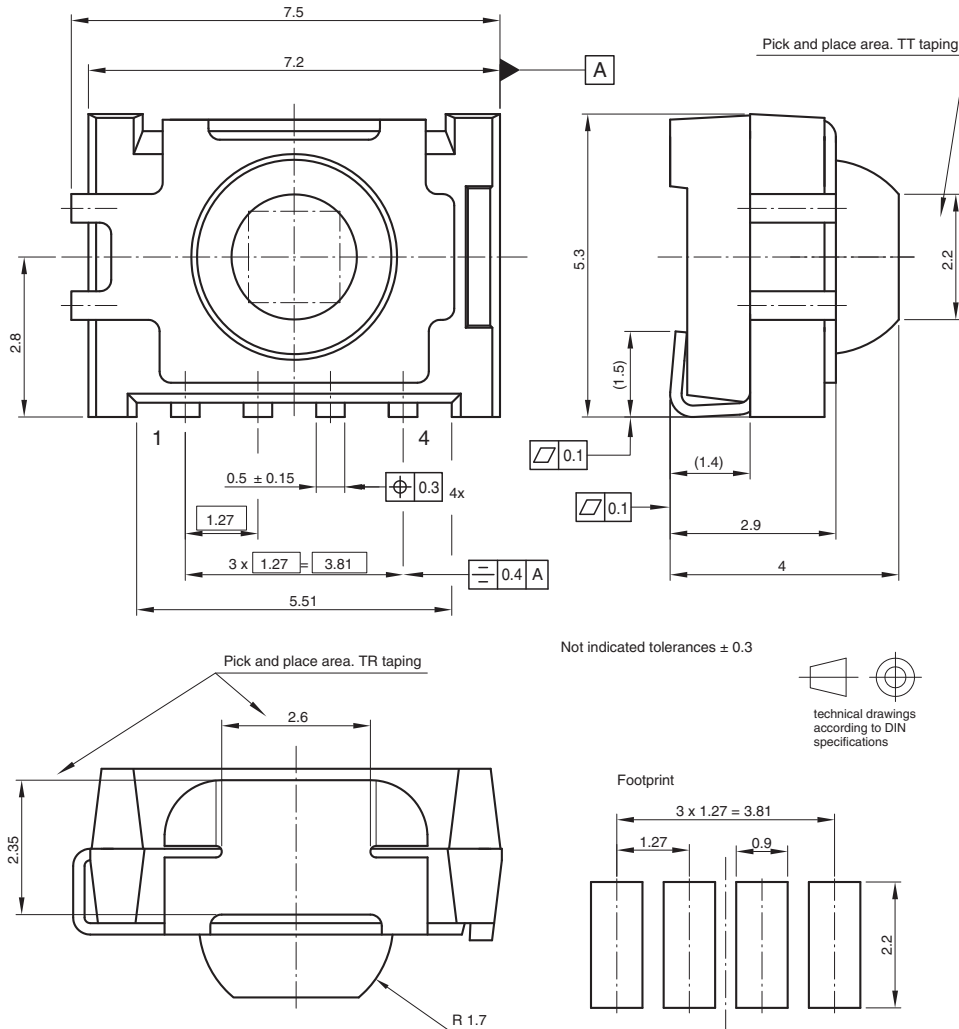
	<b>TSOP361..</b>	<b>TSOP363..</b>	<b>TSOP365..</b>
Minimum burst length	6 cycles/burst	6 cycles/burst	6 cycles/burst
After each burst of length A gap time is required of	6 to 70 cycles ≥ 10 cycles	6 to 35 cycles ≥ 10 cycles	6 to 24 cycles ≥ 10 cycles
For bursts greater than a minimum gap time in the data stream is needed of	70 cycles > 1.2 x burst length	35 cycles > 6 x burst length	24 cycles > 25 ms
Maximum number of continuous short bursts/second	2000	2000	2000
MCIR code	Yes	Preferred	Yes
RCMM code	Yes	Preferred	Yes
XMP-1, XMP-2 code	Yes	Preferred	Yes
Suppression of interference from fluorescent lamps	Mild disturbance patterns are suppressed (example: signal pattern of Fig. 13)	Complex disturbance patterns are suppressed (example: signal pattern of Fig. 14)	Critical disturbance patterns are suppressed, e.g. highly dimmed LCDs

**Notes**

- For data formats with long bursts (more than 10 carrier cycles) please see the datasheet for TSOP362.., TSOP364..



### PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.544-5341.01-4  
 Issue: 8; 02.09.09  
 16776

### ASSEMBLY INSTRUCTIONS

#### Reflow Soldering

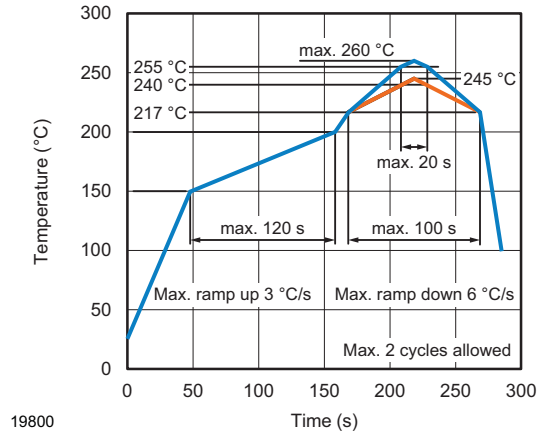
- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

#### Manual Soldering

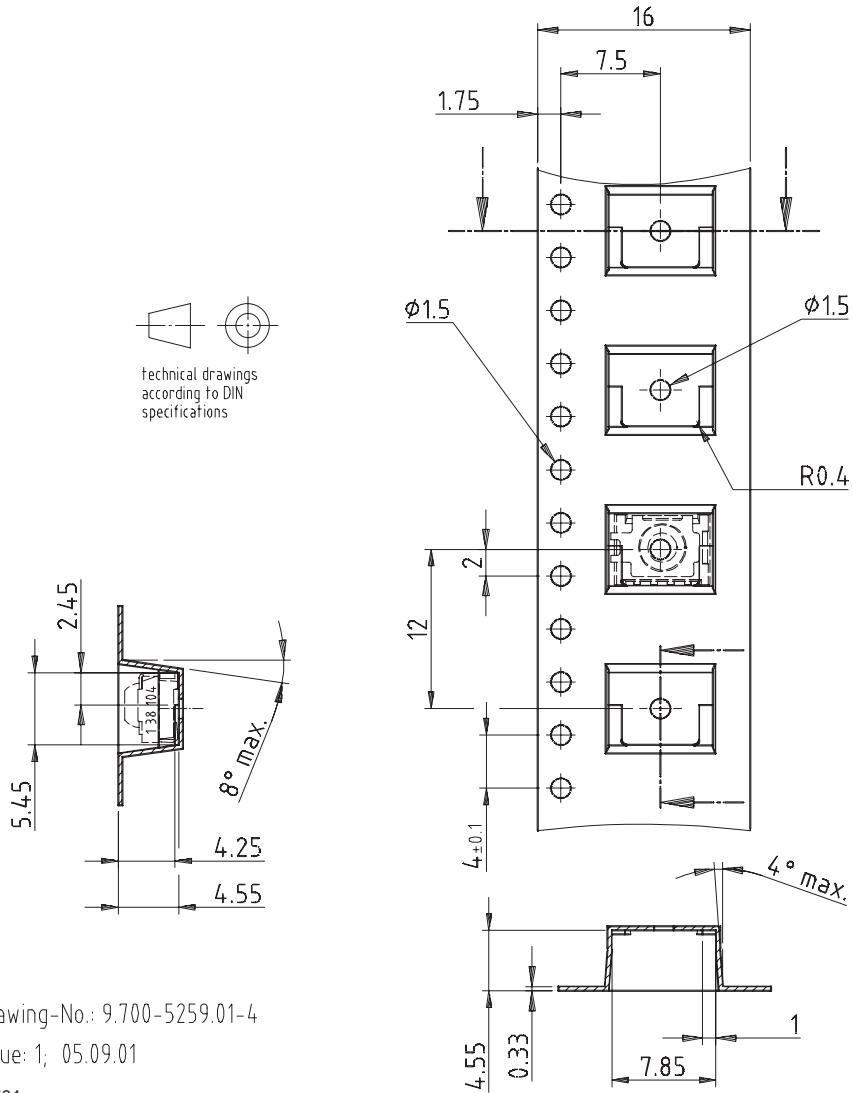
- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off.



## VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE



## TAPING VERSION TSOP..TT DIMENSIONS in millimeters



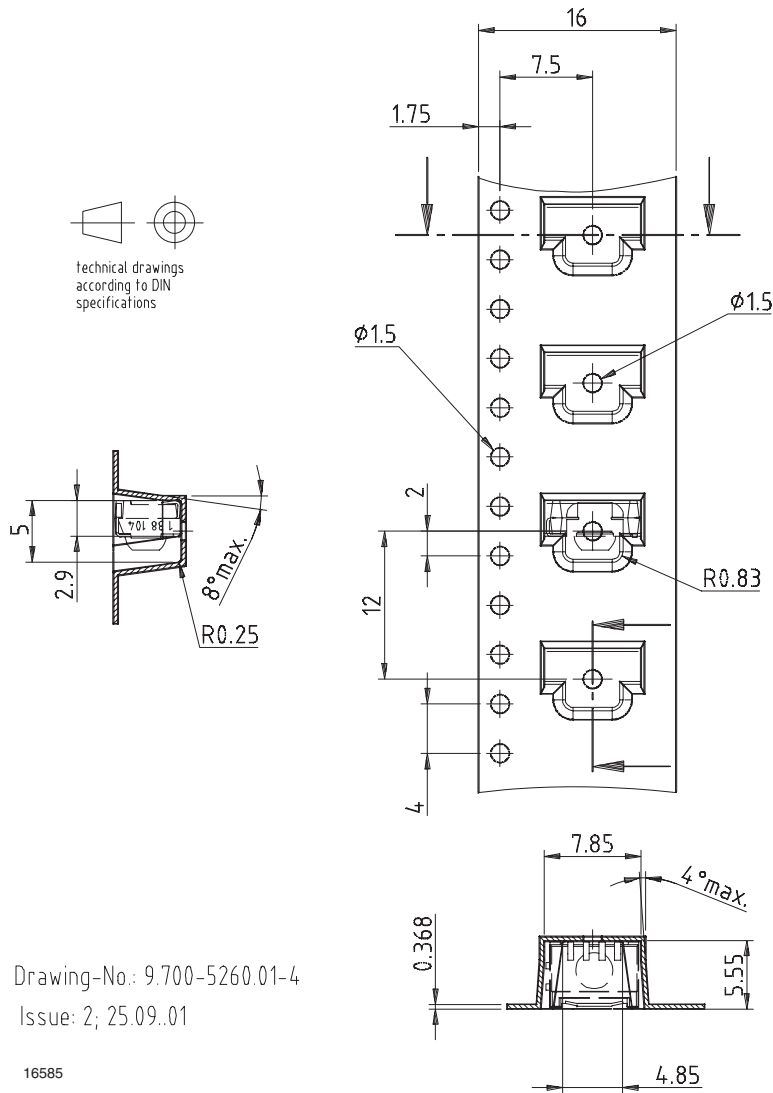
Drawing-No.: 9.700-5259.01-4

Issue: 1; 05.09.01

16584



## TAPING VERSION TSOP..TR DIMENSIONS in millimeters



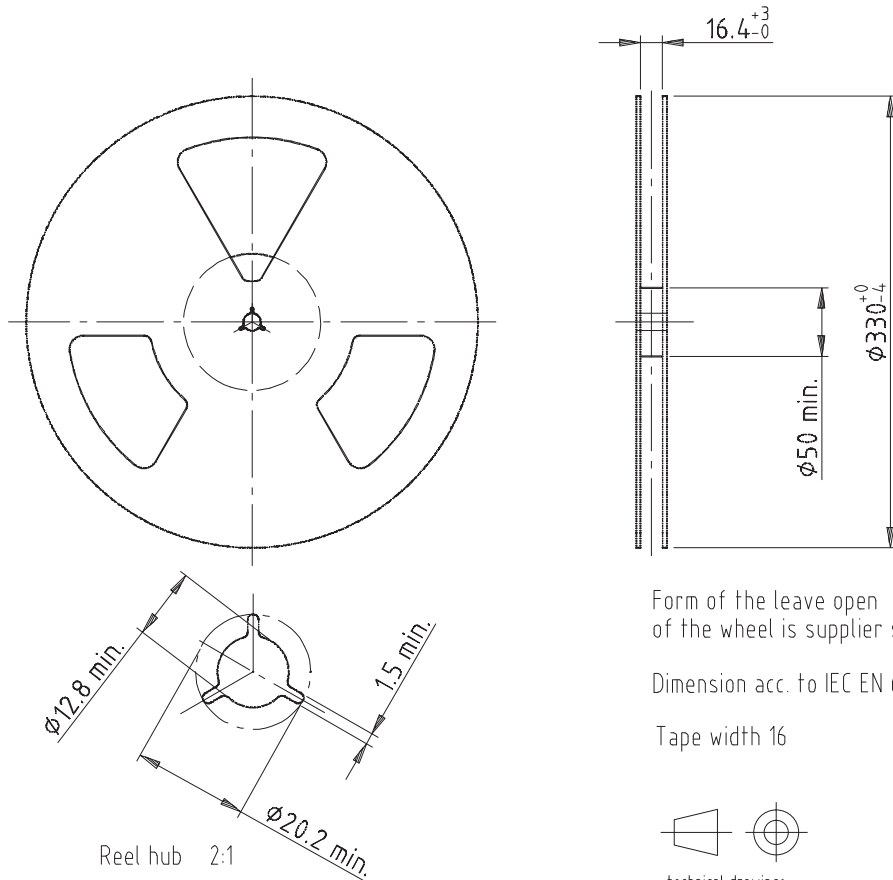
Drawing-No.: 9.700-5260.01-4

Issue: 2; 25.09.01

16585



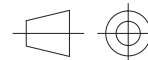
**REEL DIMENSIONS** in millimeters



Form of the leave open of the wheel is supplier specific.

Dimension acc. to IEC EN 60 286-3

Tape width 16



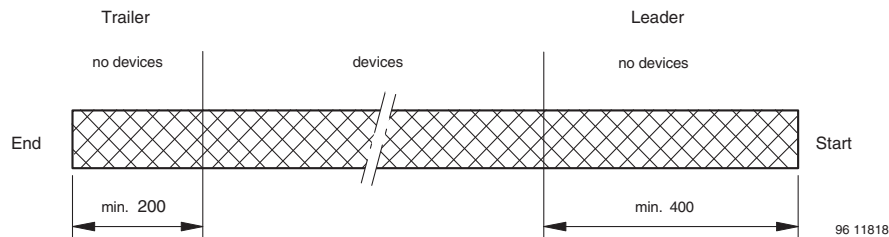
technical drawings according to DIN specifications

Drawing-No.: 9.800-5052.V2-4

Issue: 1; 07.05.02

16734

**LEADER AND TRAILER DIMENSIONS** in millimeters



**COVER TAPE PEEL STRENGTH**

According to DIN EN 60286-3

0.1 N to 1.3 N

300 mm/min. ± 10 mm/min.

165° to 180° peel angle

**LABEL**

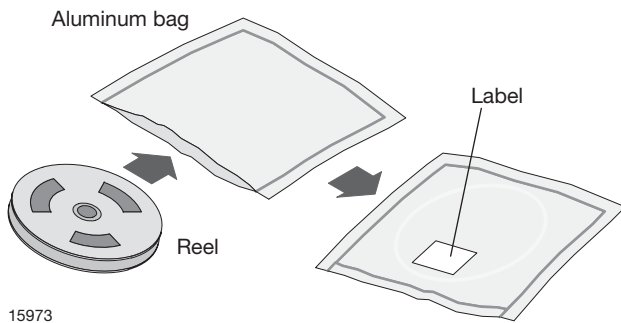
**Standard bar code labels for finished goods**

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.

VISHAY SEMICONDUCTOR GmbH STANDARD BAR CODE PRODUCT LABEL (finished goods)		
PLAIN WRITTING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
LONG BAR CODE TOP	TYPE	LENGTH
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
SHORT BAR CODE BOTTOM	TYPE	LENGTH
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17

**DRY PACKING**

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



**FINAL PACKING**

The sealed reel is packed into a cardboard box.

**RECOMMENDED METHOD OF STORAGE**

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

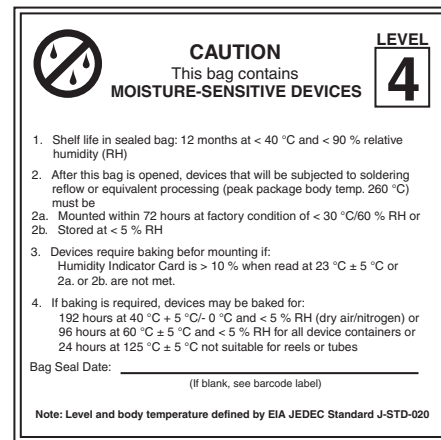
- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

After more than 72 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

- 192 h at 40 °C + 5 °C / - 0 °C and < 5 % RH (dry air / nitrogen) or
- 96 h at 60 °C + 5 °C and < 5 % RH for all device containers or
- 24 h at 125 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC® standard J-STD-020 level 4 label is included on all dry bags.



EIA JEDEC standard J-STD-020 level 4 label is included on all dry bags



### ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electrostatic sensitive devices warning labels are on the packaging.

### VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.



22645



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